Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: AIA (9QX) 010 VDFN 3x3x0.9 NiPdAu				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
		"Contained In" Sub-Component	% lotal Weight			13.56	(mg) Total	Mold Compound	% ot Total Weight	48.96
Basic Substance	CAS Number			mg/part	ppm			1		
Silica, fused Epoxy Resin	60676-86-0 Trade Secret	Mold Compound Mold Compound	42.204 2.938	11.690 0.814	422,035 29,376		Silica, fused Epoxy Resin	60676-86-0	86.20 6.00	
Phenolic Resin A	Trade Secret	Mold Compound	2.938	0.814	29,376		Phenolic Resin A	Trade Secret Trade Secret	6.00	
Aluminium hydroxide	21645-51-2	Mold Compound	0.734	0.203	7.344		Aluminium hydroxide	21645-51-2	1.50	
Carbon Black	1333-86-4	Mold Compound	0.147	0.203	1,469		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	37.993	10.524	379.928		Odiboli black	Total		
Iron	7439-89-6	Lead Frame	0.917	0.254	9,172	10.81	(mg) Total	Lead Frame	% of Total Weight	39.03
Zinc	7440-66-6	Lead Frame	0.049	0.014	488		Copper	7440-50-8	97.34	00.00
Silver	7440-22-4	Lead Frame	0.039	0.011	390		Iron	7439-89-6	2.35	
Phosphorus	7723-14-0	Lead Frame	0.032	0.009	322		Zinc	7440-66-6	0.13	
Silver	7440-22-4	Die Attach	0.477	0.132	4.774		Silver	7440-22-4	0.10	
Epoxy resin	Trade Secret	Die Attach	0.124	0.034	1,240		Phosphorus	7723-14-0	0.08	
Metal oxide	Trade Secret	Die Attach	0.019	0.005	186		-	Total	100.00	
Silicon	7440-21-3	Chip (Die)	9.110	2.523	91,100	0.17	(mg) Total	Die Attach	% of Total Weight	0.62
Doped Gold	7440-57-5	Wire Bond	0.080	0.022	800	****	Silver	7440-22-4	77.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.980	0.548	19.800		Epoxy resin	Trade Secret	20.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.110	0.030	1,100		Metal oxide	Trade Secret	3.00	
Gold	7440 57 5	Disting an entermal lands (sins)	0.440	0.030	1,100			Total	100.00	
Gold	7440-57-5	Plating on external leads (bins)	0.110							
Gold	7440-57-5	Plating on external leads (pins) TOTA		27.700	1,000,000	2.52	(mg) Total		% of Total Weight	9.11
niconductor device and its homogenous materials o	0.0277 g	Total Mass	S: 100.000	27.700	1,000,000	2.52	(mg) Total Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	9.11
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miconductor device and its homogenous materials on a 2002/53/EC (End-of-Life Vehicles (ELV) without exance with the above EU Directives has been verified mical substance is absent from the list above, the characted's knowledge and belief as of the date of this diverse.	0.0277 g omply with EU Directives: 201 emption (zero) via internal design controls, s emical substance is NOT an i ocument, there is no credible	TOTA Total Mass 02/95/EC (27 January 2003) & Directive 2011/65/EU supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device a reason to believe that the unavoidable impurity con	S: 100.000 (08 June 2011) a	27.700 and 2015/863/E	1,000,000 EU (31 March echnology		Doped Silicon	7440-21-3 Total	100.00	
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